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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Present Application:

Applicants: Salman Akram, Alan G. Wood,
and Warren M. Farnworth

Attorney Docket No.: 500185.03

Date : August 4, 2000

Title : APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED
DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER

Prior Application:

Examiner : Lourdes C. Cruz

Art Unit : 2815

Serial No. : 09/389,862

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

Prior to substantive examination, please amend the above-identified
application as follows:

In the Specification:

Amend the specification by inserting a new section before the "Technical
Field" as follows:

-- CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of pending United States Patent Application
No. 09/389,862, filed September 2, 1999. --

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In the Claims:

Please amend the claims as follows:

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1. (Amended) A semiconductor device, comprising:
 a bumped device having a plurality of conductive bumps formed thereon;
 a substrate having a plurality of pockets disposed therein and a plurality of contact pads distributed thereon and approximately aligned with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and
 an anisotropically conductive layer disposed between and mechanically coupled to the bumped device and to the substrate, the anisotropically conductive layer electrically coupling each of the conductive bumps with a corresponding one of the contact pads.

✓ Please cancel claim 2.

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3. (Amended) The semiconductor device of claim 1 wherein [the substrate includes a plurality of pockets disposed therein, the contact pads being at least partially disposed within the pockets and] the conductive bumps are [being] at least partially engaged within the pockets.

✓ Please cancel claim 4.

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9. (Amended) An apparatus for testing a bumped device having a plurality of conductive bumps, comprising:
 a substrate including a first surface having a plurality of pockets disposed therein and a plurality of contact pads distributed thereon, the contact pads being substantially alignable with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and

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concl'd.*

an anisotropically conductive layer disposed on the first surface and engageable with the plurality of conductive bumps to electrically couple each of the conductive bumps with a corresponding one of the contact pads.

✓ Please cancel claims 13-14.

✓ Please cancel claims 18-58.


REMARKS

Following above-noted preliminary amendments, claims 1, 3, 5-12, and 15-17 are pending in the present application. Applicants respectfully request consideration and allowance of same.

If there are any remaining matters that can be handled in a telephone conference, Applicant invites the Examiner to phone his attorney, Dale C. Barr, at (206) 903-8745.

Respectfully submitted,

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